

GS320C

3.0AMPS . GLASS PASSIVATED RECTIFIERS

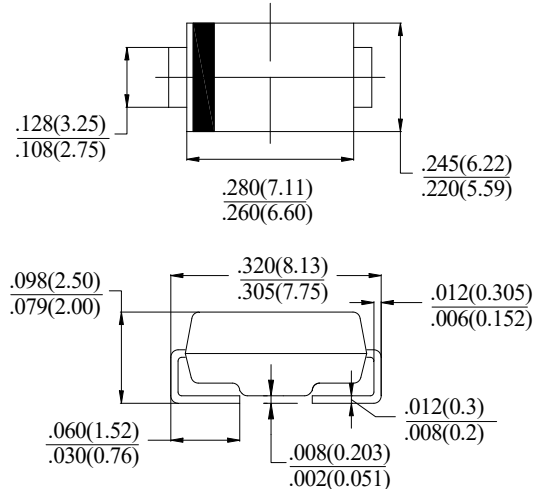
FEATURE

- . High current capability
- . Low forward voltage drop
- . Low power loss, high efficiency
- . High surge capability
- . High temperature soldering guaranteed:
260°C/10 seconds at terminals.
- . For surface mounted application.
- . Easy pick and place.

MECHANICAL DATA

- . Terminal: Solder plated
- . Case: Molded with UL-94 Class V-0 recognized
Flame Retardant Epoxy (free halogen)
- . Polarity: color band denotes cathode

SMC (DO-214AB)



Dimensions in inches and (millimeters)

MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Ratings at 25°C ambient temperature unless otherwise specified.

Single phase, half wave, 60Hz, resistive or inductive load. For capacitive load, derate current by 20%

Type Number	SYM BOL	GS320C	units
Maximum Recurrent Peak Reverse Voltage	V_{RRM}	2000	V
Maximum RMS Voltage	V_{RMS}	1400	V
Maximum DC blocking Voltage	V_{DC}	2000	V
Maximum Average Forward Rectified Current at $T_L=90^\circ\text{C}$	$I_{F(AV)}$	3.0	A
Peak Forward Surge Current @ $T_J=25^\circ\text{C}$ 8.3ms single half sine-wave @ $T_J=125^\circ\text{C}$	I_{FSM}	100 80	A
Peak Forward Surge Current @ $T_J=25^\circ\text{C}$ 1.0ms single half sine-wave @ $T_J=125^\circ\text{C}$	I_{FSM}	200 160	A
I^2t Rating for Fusing ($t < 8.3\text{ms}$)	I^2t	41.5	AzSec
Maximum Forward Voltage at 3.0 A DC	V_F	1.2	V
Maximum DC Reverse Current @ $T_J=25^\circ\text{C}$ at rated DC blocking voltage @ $T_J=125^\circ\text{C}$	I_R	5.0 100.0	μA
Typical Junction Capacitance (Note1)	C_J	35	pF
Maximum Reverse Recovery Time (Note2)	t_{rr}	7500	nS
Typical Thermal Resistance (Note 3)	$R_{(JA)}$	45	$^\circ\text{C/W}$
	$R_{(JC)}$	15	
	$R_{(JL)}$	18	
Storage Temperature	T_{STG}	-55 to +150	$^\circ\text{C}$
Operation Junction Temperature	T_J	-55 to +150	$^\circ\text{C}$

Note:

1. Measured at 1.0 MHz and applied reverse voltage of 4.0Vdc
2. Reverse Recovery test Condition: $I_F=0.5\text{A}$, $I_R=1.0\text{A}$, $IRR=0.25\text{A}$
3. Measured on P. C. Board with 0.2×0.2 " ($5.0 \times 5.0\text{mm}$) Copper Pad Areas.

RATING AND CHARACTERISTIC CURVES

FIG.1-TYPICAL FORWARD CURRENT DERATING CURVE

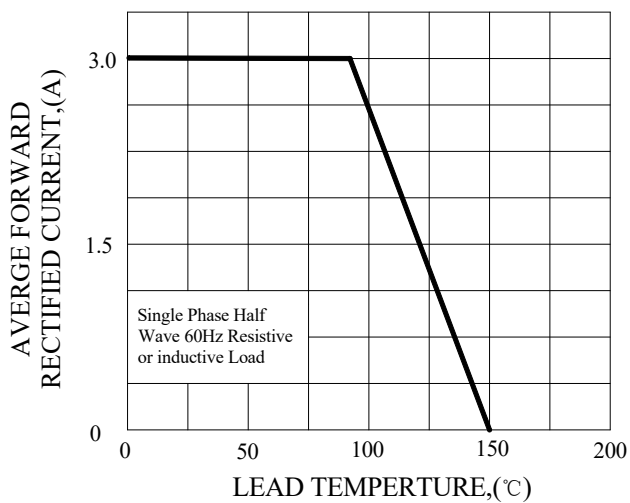


FIG.2-TYPICAL INSTANTANEOUS FORWARD CHARACTERISTICS

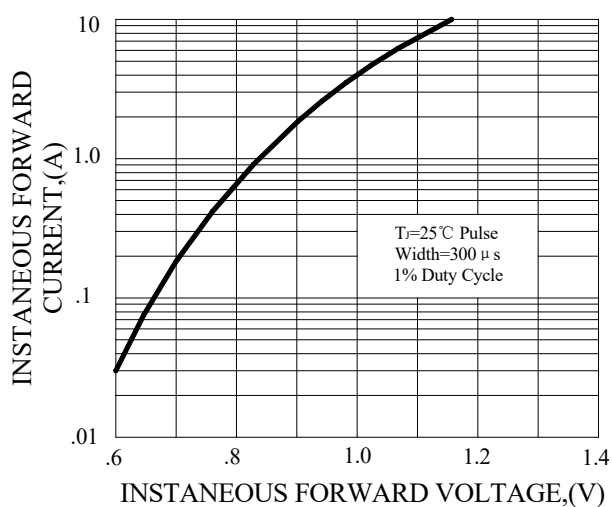


FIG.3-MAXIMUN NON-REPETITIVE FORWARD SURGE CURRENT

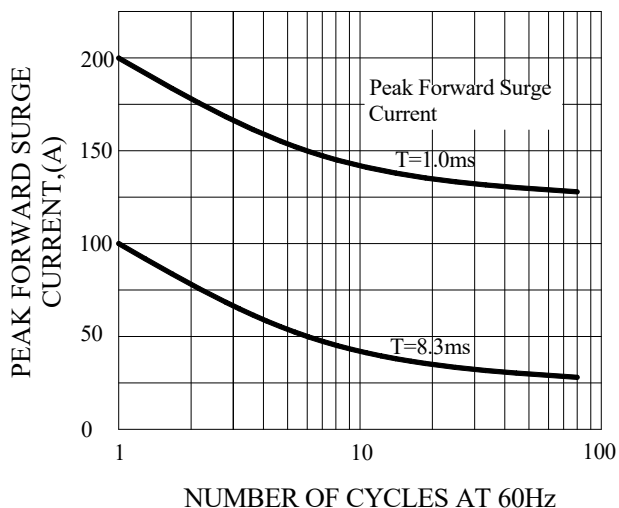
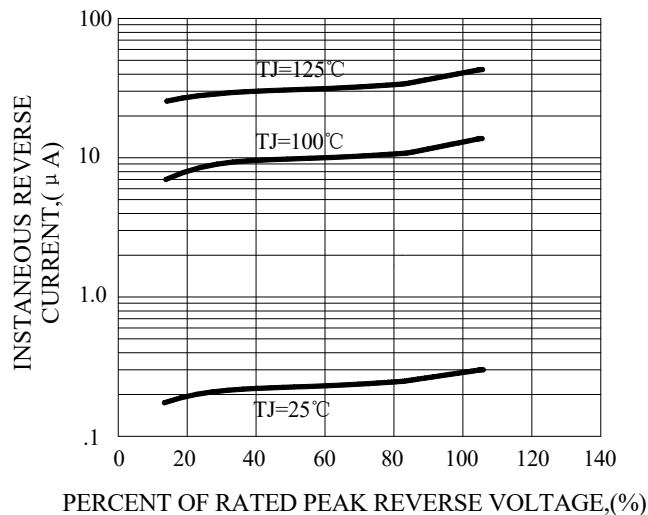
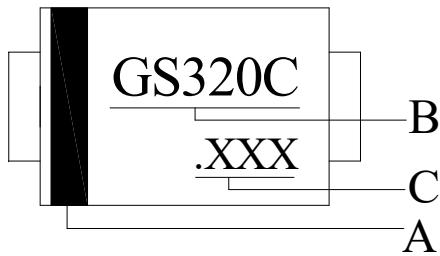


FIG.4-TYPICAL REVERSE CHARACTERISTICS



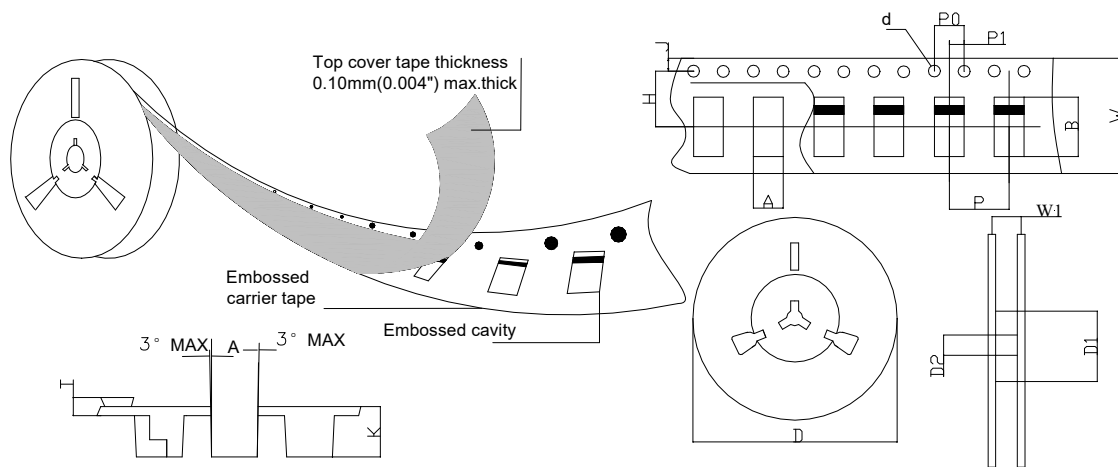
Marking and packaging illustration

1、Marking



SYMBOL	Explanation
A	Color Band Denotes Cathode
B	Product Name
C	Date Code

2、Packaging



SPECIFICATIONS mm(inch)		PACKAGE	SPECIFICATIONS mm(inch)		PACKAGE
ITEM	SYM BOL	SMC (DO-214AB)	ITEM	SYM BOL	SMC (DO-214AB)
Carrier width	A	6.15(0.242)Max	Carrier depth	K	2.54(0.100)Typ
Carrier length	B	8.41(0.331)Max	Punch hole pitch	P	8.00(0.315)Typ
Sprocket hole	d	ø1.55(0.061)Typ	Sprocket hole pitch	P0	4.00(0.157)Typ
Reel outer diameter	D	330.0(13.0)Typ	Embossment center	P1	2.00(0.079)Typ
Reel inner diameter	D1	74.0(2.913)Min	Overall tape thickness	T	0.25(0.010)Typ
Feed hole diameter	D2	13.0(0.512)Typ	Tape width	W	16.0(0.430)Typ
Sprocket hole position	J	1.75(0.069)Typ	Reel width	W1	16.5(0.650)Min
Punch hole position	H	7.50(0.295)Typ			